

Data Sheet Issue:- 3

Phase Control Thyristor Types N1479NC240 to N1479NC300

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V _{DRM}	Repetitive peak off-state voltage, (note 1)	2400-3000	V
V _{DSM}	Non-repetitive peak off-state voltage, (note 1)	2400-3000	V
V _{RRM}	Repetitive peak reverse voltage, (note 1)	2400-3000	V
V _{RSM}	Non-repetitive peak reverse voltage, (note 1)	2500-3100	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
I _{T(AV)}	Mean on-state current. T _{sink} =55°C, (note 2)	1436	А
I _{T(AV)}	Mean on-state current. T _{sink} =85°C, (note 2)	989	А
I _{T(AV)}	Mean on-state current. T _{sink} =85°C, (note 3)	602	А
I _{T(RMS)}	Nominal RMS on-state current. T _{sink} =25°C, (note 2)	2830	А
I _{T(d.c.)}	D.C. on-state current. T _{sink} =25°C, (note 4)	2466	А
I _{TSM}	Peak non-repetitive surge t_p =10ms, V_{RM} =0.6 V_{RRM} , (note 5)	21	kA
I _{TSM2}	Peak non-repetitive surge $t_p=10ms$, $V_{RM}\leq10V$, (note 5)	23	kA
l ² t	$I^{2}t$ capacity for fusing t_{p} =10ms, V_{RM} =0.6 V_{RRM} , (note 5)	2.21×10 ⁶	A ² s
l ² t	$I^{2}t$ capacity for fusing t _p =10ms, V _{RM} ≤10V, (note 5)	2.65×10 ⁶	A ² s
(]; (](Maximum rate of rise of on-state current (repetitive), (Note 6)	200	A/µs
(di/dt) _{cr}	Maximum rate of rise of on-state current (non-repetitive), (Note 6)	400	A/µs
V _{RGM}	Peak reverse gate voltage	5	V
P _{G(AV)}	Mean forward gate power	4	W
P _{GM}	Peak forward gate power	30	W
V_{GD}	Non-trigger gate voltage, (Note 7)	0.25	V
T _{HS}	Operating temperature range	-40 to +125	°C
T _{stg}	Storage temperature range	-40 to +150	°C

Notes: -

- 1) De-rating factor of 0.13% per °C is applicable for T_j below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 125°C T_i initial.
- 6) $V_D=67\% V_{DRM}$, $I_{TM}=3000A$, $I_{FG}=2A$, $t_r \le 0.5 \mu s$, $T_{case}=125^{\circ}C$.
- 7) Rated V_{DRM}.

Characteristics

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
V _{TM}	Maximum peak on-state voltage	-	-	1.9	I _{TM} =2550A	V
V _{T0}	Threshold voltage	-	-	1.0		V
r _T	Slope resistance	-	-	0.342		mΩ
(dv/dt) _{cr}	Critical rate of rise of off-state voltage	1000	-	-	V _D =80% V _{DRM} , linear ramp	V/µs
I _{DRM}	Peak off-state current	-	-	100	Rated V _{DRM}	mA
I _{RRM}	Peak reverse current	-	-	100	Rated V _{RRM}	mA
V _{GT}	Gate trigger voltage	-	-	3.0		V
I _{GT}	Gate trigger current	-	-	300	$T_j=25^{\circ}C, V_D=10V, I_T=2A$	mA
I _H	Holding current	-	-	1000	T _j =25°C	mA
t _{gd}	Gate controlled turn-on delay time	-	0.6	1.5	V _D =80%V _{DRM} , I _{TM} =2000A, di/dt=10A/µs,	
t _{gt}	Turn-on time	-	1.2	2.5	I_{FG} =2A, t _r =0.5µs, T _j =25°C	μs
Q _{rr}	Recovered Charge	-	3600	-		μC
Q _{ra}	Recovered Charge, 50% chord	-	2700	2900		μC
Irm	Reverse recovery current	-	140	-	I_{TM} =1000A, t _p =1ms, di/dt=10A/µs, V _r =50V	А
t _{rr}	Reverse recovery time, 50% chord	-	40	-		μs
t _q	Turn-off time	-	390	500	I _{TM} =1000A, t _p =1ms, di/dt=10A/μs, V _r =50V, V _{dr} =80%V _{DRM} , dV _{dr} /dt=20V/μs	
		-	560	700	I _{TM} =1000A, t _p =1ms, di/dt=10A/μs, V _r =50V, V _{dr} =80%V _{DRM} , dV _{dr} /dt=200V/μs	μs
R _{thJK}	Thermal resistance, junction to heatsink	-	-	0.022	Double side cooled	K/W
		-	-	0.044	Single side cooled	K/W
F	Mounting force	19	-	26		kN
W _t	Weight	-	510	-		g

Notes: -

1) Unless otherwise indicated $T_j=125^{\circ}C$.

Notes on Ratings and Characteristics

1.0 Voltage Grade Table

Voltage Grade	V _{DRM} V _{DSM} V _{RRM} V	V _{RSM} V	V _D V _R DC V
24	2400	2500	1450
26	2600	2700	1550
28	2800	2900	1650
30	3000	3100	1750

2.0 Extension of Voltage Grades

This report is applicable to other and higher voltage grades when supply has been agreed by Sales/Production.

3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T_i below 25°C.

<u>4.0 Repetitive dv/dt</u> Standard dv/dt is 1000V/µs.

5.0 Snubber Components

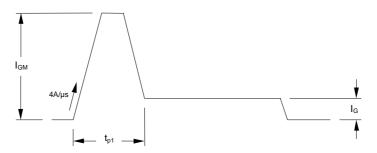
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 600A/µs at any time during turnon on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 300A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of I_{GM} should be between five and ten times I_{GT} , which is shown on page 2. Its duration (t_{p1}) should be 20µs or sufficient to allow the anode current to reach ten times I_L , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current I_G should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times I_{GT} .

8.0 Computer Modelling Parameters

8.1 Device Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{V_{T0}^{2} + 4 \cdot ff \cdot r_{T} \cdot W_{AV}}}{2 \cdot ff \cdot r_{T}} \text{ and:} \qquad \begin{aligned} W_{AV} = \frac{\Delta T}{R_{th}} \\ \Delta T = T_{j\max} - T_{Hs} \end{aligned}$$

Where V_{T0} =1.0V, r_T=0.342m Ω ,

 R_{th} = Supplementary thermal impedance, see table below.

ff = Form factor, see table below.

Supplementary Thermal Impedance							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave Double Side Cooled	0.0312	0.0285	0.0267	0.0255	0.0240	0.0228	0.0220
Square wave Single Side Cooled	0.0543	0.0513	0.0496	0.0484	0.0469	0.0455	0.0440
Sine wave Double Side Cooled	0.0256	0.0246	0.0239	0.0233	0.022		
Sine wave Single Side Cooled	0.0509	0.0482	0.0471	0.0463	0.044		

Form Factors							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.46	2.45	2	1.73	1.41	1.15	1
Sine wave	3.98	2.78	2.22	1.88	1.57		

8.2 Calculating V_T using ABCD Coefficients

The on-state characteristic I_T vs. V_T , on page 6 is represented in two ways;

- (i) the well established V_{T0} and r_T tangent used for rating purposes and
- (ii) a set of constants A, B, C, D, forming the coefficients of the representative equation for V_T in terms of I_T given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for V_T agree with the true device characteristic over a current range, which is limited to that plotted.

25°C Coefficients		125°C Coefficients		
Α	1.136175	Α	2.01023758	
В	-0.03504027	В	-0.2896884	
С	2.065692×10 ⁻⁴	С	8.03792×10 ⁻⁵	
D	8.168895×10 ⁻³	D	0.03875571	

8.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}}\right)$$

Where p = 1 to *n*, *n* is the number of terms in the series and:

- t = Duration of heating pulse in seconds.
- $r_{t} =$ Thermal resistance at time t.
- r_p = Amplitude of p_{th} term.

 τ_p = Time Constant of r_{th} term.

D.C. Double Side Cooled							
Term	Term 1 2 4 5						
rp	3.424745×10 ⁻³	1.745273×10 ⁻³	8.532017×10 ⁻⁴	3.457329×10 ⁻⁴			
$ au_{ m p}$	1.125391	0.1878348	0.02788979	8.430889×10 ⁻³			

D.C. Single Side Cooled							
Term	erm 1 2 5 6						
r _p	8.375269×10 ⁻³	2.518437×10 ⁻³	1.193758×10 ⁻³	7.45432×10 ⁻⁴			
$ au_p$	8.929845	0.4711304	0.08221244	0.01221961			

9.0 Reverse recovery ratings

(i) Q_{ra} is based on 50% I_{rm} chord as shown in Fig. 1.

(ii) Q_{rr} is based on a 150µs integration time.

i.e.
$$Q_{rr} = \int_{0}^{150\,\mu s} i_{rr}.dt$$

(iii)
$$K \ Factor = \frac{t1}{t2}$$

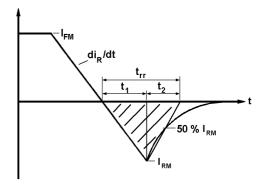


Fig. 1

<u>Curves</u>

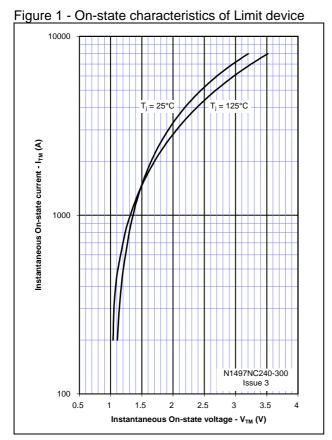
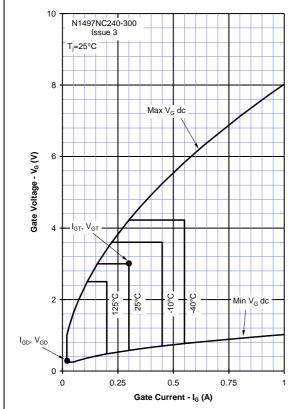
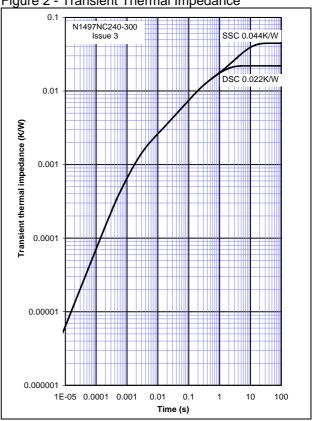


Figure 3 - Gate Characteristics - Trigger Limits





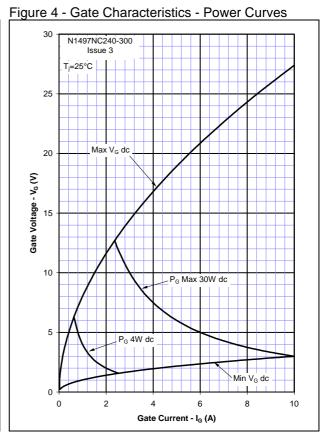


Figure 2 - Transient Thermal Impedance



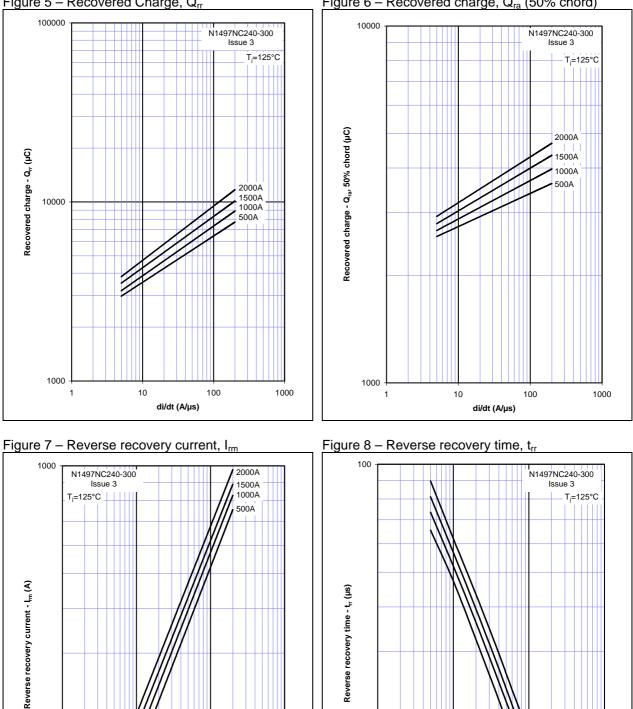
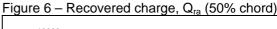


Figure 5 – Recovered Charge, Qn



10

di/dt (A/µs)

100

1

1000

100

10

1

10

di/dt (A/µs)

1000

2000A 1500A 1000A 500A

100



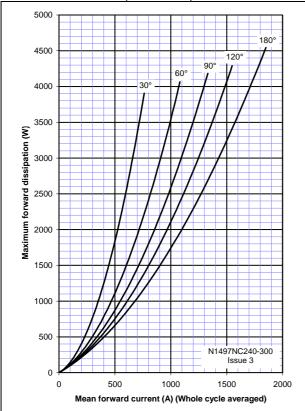


Figure 9 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

Figure 10 – On-state current vs. Heatsink temperature - Double Side Cooled (Sine wave)

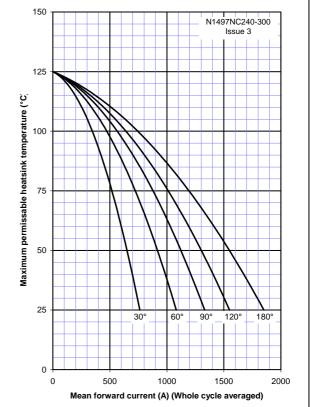


Figure 11 – On-state current vs. Power dissipation – Double Side Cooled (Square wave)

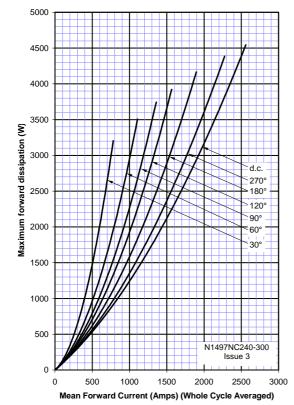
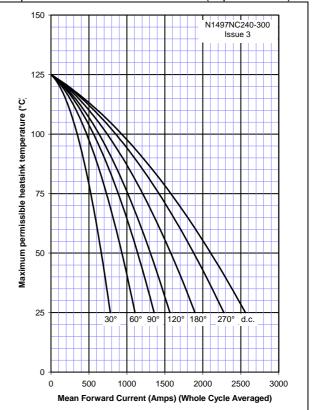


Figure 12 – On-state current vs. Heatsink temperature - Double Side Cooled (Square wave)



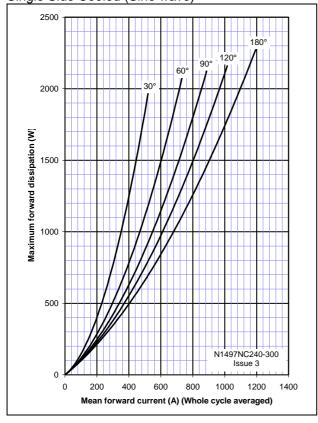


Figure 13 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)

Figure 14 – On-state current vs. Heatsink temperature - Single Side Cooled (Sine wave)

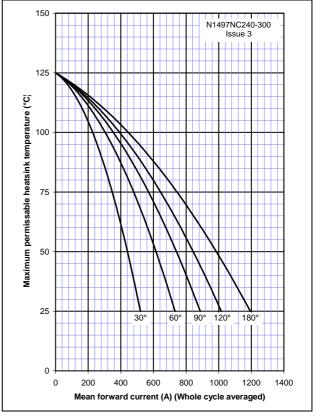


Figure 15 – On-state current vs. Power dissipation – Single Side Cooled (Square wave)

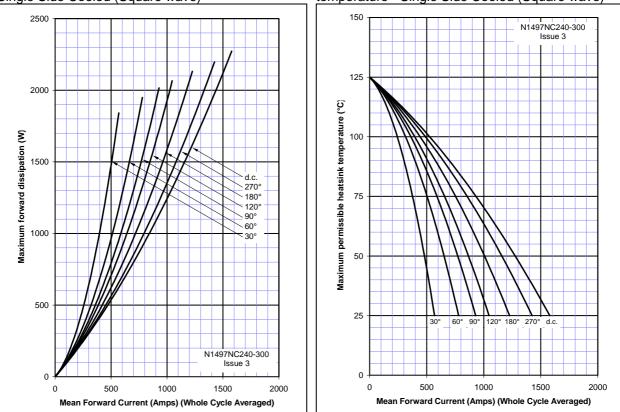


Figure 16 – On-state current vs. Heatsink temperature - Single Side Cooled (Square wave)

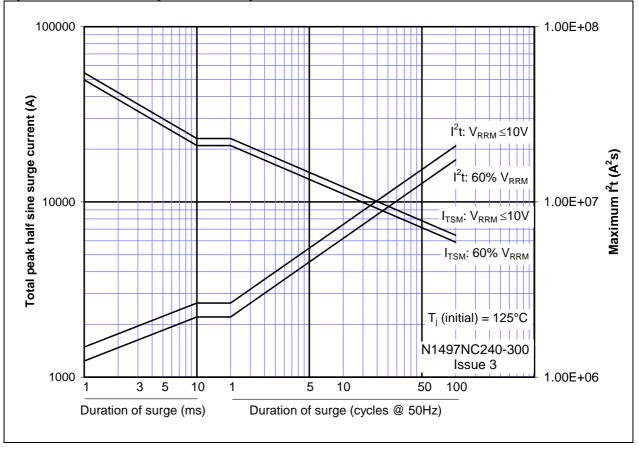


Figure 17 – Maximum surge and I²t Ratings



Outline Drawing & Ordering Information

